CBTU02043

High-speed differential 1-to-2 switch

Rev. 3 — 19 July 2018 Product data sheet

1. General description

CBTU02043 is a high-speed differential 1-to-2 switch chip optimized to interface with USB Type-C connector for mobile and PC applications. This high performance switch chip can be used for single port USB3.1, PCIe-Gen3, MIPI high-speed serial interface applications. It can also support DP1.4 or 4 single-ended DDR channels. The CBTU02043 chip can also provide 2-to-1 MUX function by selecting 1 (Port A) out of two differential ports (Port B or C) for other applications.

The pinouts are optimized for USB3.1 Type-C DeMUX application and achieve very low crosstalk to meet the stringent USB Type-C crosstalk spec. The small package and pinning is ideal for smartphone USB Type-C application.

CBTU02043 is available in 1.6 mm x 2.4 mm x 0.5 mm HUQFN16 package with 0.4 mm pitch.

2. Features and benefits

- Optimized for USB Type-C connector PCB routing for signal integrity
  - Minimize crosstalk to meet stringent USB Type-C requirement
  - Minimize via with friendly USB Type-C PCB layout
- One port (two bidirectional differential channels) 1-to-2 switch
  - Low insertion loss: −1.4 dB at 5 GHz; −0.9 dB at 2.5 GHz; −0.5 dB at 100 MHz
  - Low off-state isolation: −20 dB at 5 GHz; −40 dB at 100 MHz
  - Low return loss: −16 dB at 2.5 GHz; −12 dB @ 5 GHz
  - Low ON-state resistance: 10 Ω (typ)
  - Bandwidth: 12 GHz (typ)
  - Very low DDNEXT crosstalk: < −37 dB at 5 GHz
  - VIC common mode input voltage VIC: 0 V to 2 V
  - Differential input voltage VID: <1.6 V
  - Intra-pair skew: <6 ps
- VDD Power Supply voltage range: 1.62 V to 3.63 V
- Low current consumption:
  - 200 μA (typ) for active mode
  - 3 μA (typ) for power-saving
- CMOS SEL and XSD pins
- Back current protection on all I/O pins of these switches
- Patent pending high performance analog pass-gate technology
- All channels support rail-to-rail input voltage (up to 2.4 V)
- HUQFN16 1.6 mm × 2.4 mm × 0.5 mm package with 0.4 mm pitch

- ESD: 2000 V HBM; 1000 V CDM
- Operating temperature range: −10 °C to 85 °C

3. Application diagram

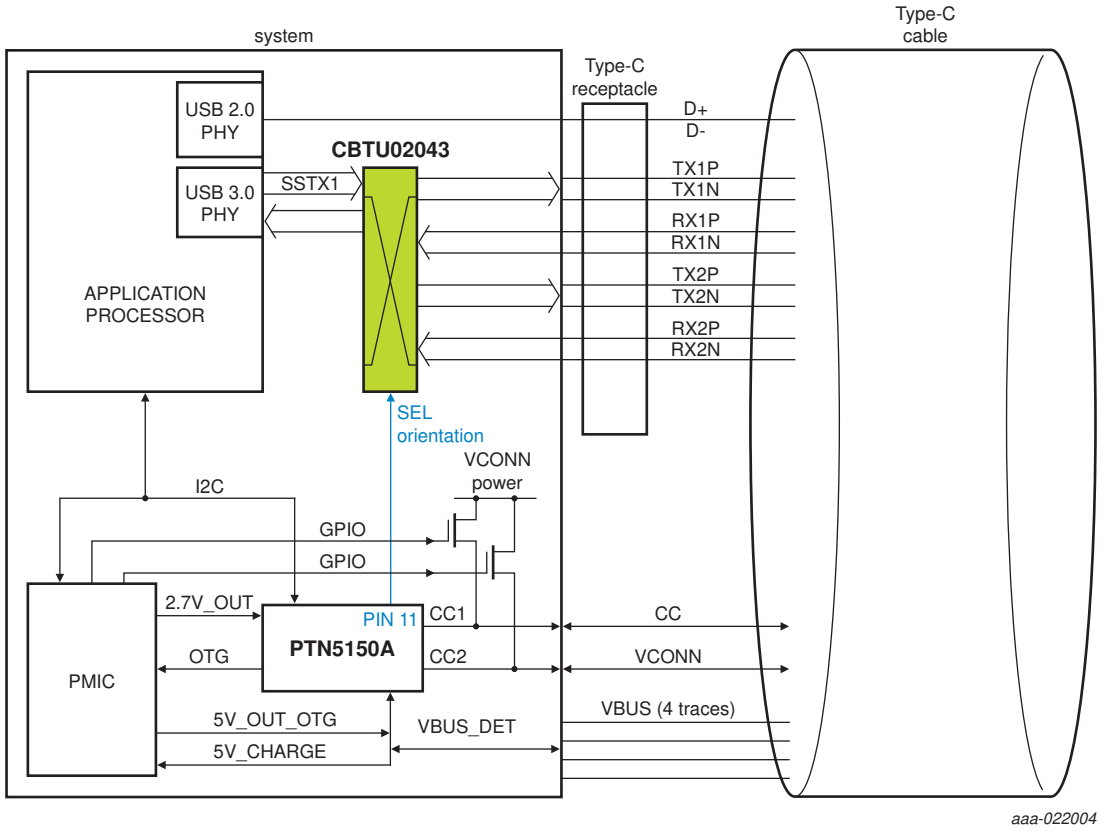


Fig 1. Application diagram

4. Ordering information

Table 1. Ordering information

Type number	Topside marking	Package		
		Name	Description	Version
CBTU02043HE	43	HUQFN16	Plastic, super thin quad flat package; no leads; 16 terminals; body 1.6 mm x 2.4 mm x 0.5 mm; 0.4 mm pitch	SOT1832-1

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4.1 Ordering options

Table 2. Ordering options

Type number	Orderable part number	Package	Packing method	Minimum order quantity	Temperature
CBTU02043HE[1]	CBTU02043HEJ	HUQFN16	REEL 13" Q1/T1 *STANDARD MARK SMD	10000	T_{amb} = −10 °C to +85 °C

[1] In development. Contact your NXP sales office for availability.

5. Block diagram

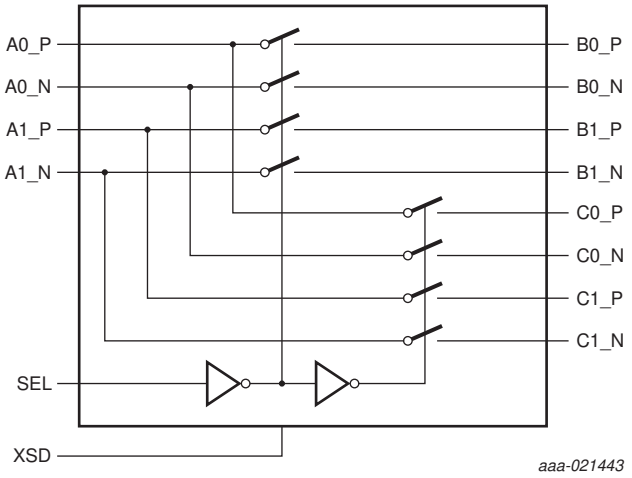


Fig 2. Block diagram

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6. Pinning information

6.1 Pinning

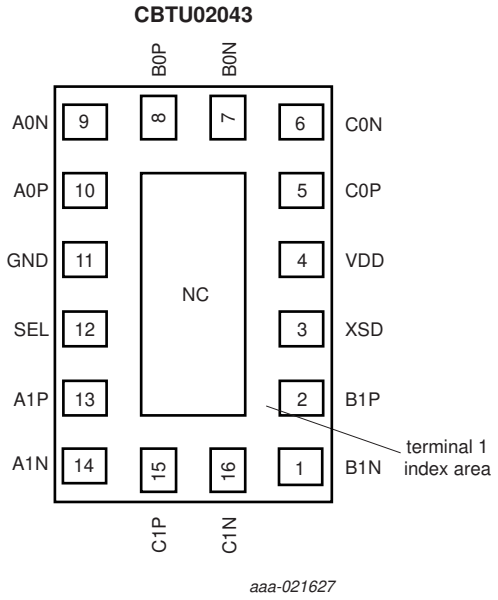


Fig 3. Pin configuration for HUQFN16 (transparent top view)

Refer to Section 12 “Package outline” for package related information.

6.2 Pin description

Table 3. Pin description

Symbol	Pin	Type	Description
Data path signals			
A0N	9	differential I/O	USB3.1 differential TX signals for A port
A0P	10	differential I/O	
B0P	8	differential I/O	USB3.1 differential TX signals for B port
B0N	7	differential I/O	
C0N	6	differential I/O	USB3.1 differential TX signals for C port
C0P	5	differential I/O	
A1P	13	differential I/O	USB3.1 differential RX signals for A port
A1N	14	differential I/O	
B1P	2	differential I/O	USB3.1 differential RX signals for B port
B1N	1	differential I/O	
C1N	16	differential I/O	USB3.1 differential RX signals for C port
C1P	15	differential I/O	

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Table 3. Pin description *...continued*

Symbol	Pin	Type	Description
Control signal			
SEL	12	GPIO input	Input signal driven by GPIO When SEL = LOW, Port A and Port B are mutually connected When SEL = HIGH, port A and port C are mutually connected
XSD	3	CMOS input	Shutdown pin; should be driven LOW for normal operation. When HIGH, all paths are switched off (high impedance state). And supply current consumption is minimized.
Power supply			
VDD	4	power	Power supply range between 1.62 V and 3.63 V
Ground connection			
GND	11	ground	0 V; must connect to PCB ground
NC	center pad	not connected	Center pad is not connected to the device ground pin inside the package. Recommend to connect center pad to PCB ground

7. Functional description

Refer to Figure 2 “Block diagram” of CBTU02043.

The CBTU02043 provides a shutdown function to minimize power consumption when the application is not active, but power to the CBTU02043 is provided. The XSD pin (power down HIGH) places all channels in high -impedance state while reducing current consumption to near-zero. When XSD pin is LOW, the device operates normally.

Table 4. ON/OFF control table

XSD	SEL	Function
HIGH	X	A, B and C ports are high-Z
LOW	LOW	A to B ports and vice versa
LOW	HIGH	A to C ports and vice versa

8. Application examples

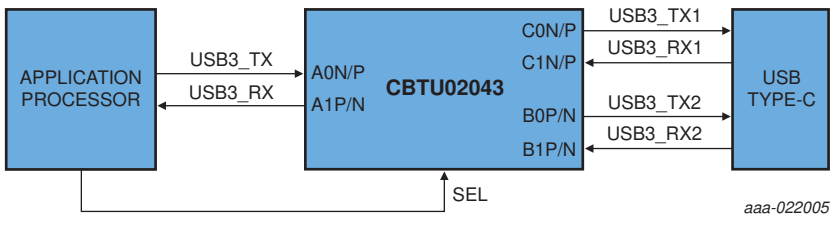


Fig 4. USB Type-C smartphone application

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9. Limiting values

Table 5. Limiting values [1]

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
V_{DD}	supply voltage		[2]	−0.3	+4.4	V
V_I	input voltage of control pins		[2]	−0.3	+4.4	V
V_{IO}	voltage of I/O pins of switches		[2]	−0.3	+2.6	V
T_{stg}	storage temperature			−65	+150	°C
V_{ESD}	electrostatic discharge voltage	HBM	[3]	-	2000	V
		CDM	[4]	-	1000	V

[1] Stresses beyond those listed under absolute maximum ratings may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any conditions beyond those indicated under recommended operating conditions is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

[2] All voltage values, except differential voltages, are with respect to network ground terminal.

[3] Human Body Model: ANSI/EOS/ESD-S5.1-1994, standard for ESD sensitivity testing, Human Body Model - Component level; Electrostatic Discharge Association, Rome, NY, USA.

[4] Charged Device Model: ANSI/EOS/ESD-S5.3-1-1999, standard for ESD sensitivity testing, Charged Device Model - Component level; Electrostatic Discharge Association, Rome, NY, USA.

10. Recommended operating conditions

Table 6. Operating conditions

Over operating free-air temperature range (unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
VDD	supply voltage	3.3 V supply option	1.62	-	3.63	V
V_I	input voltage	CMOS inputs	−0.3	-	VDD	V
		switch I/O pins	−0.3	-	+2.4	V
T_{amb}	ambient operating temperature	operating in free air	−10	-	+85	°C

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11. Characteristics

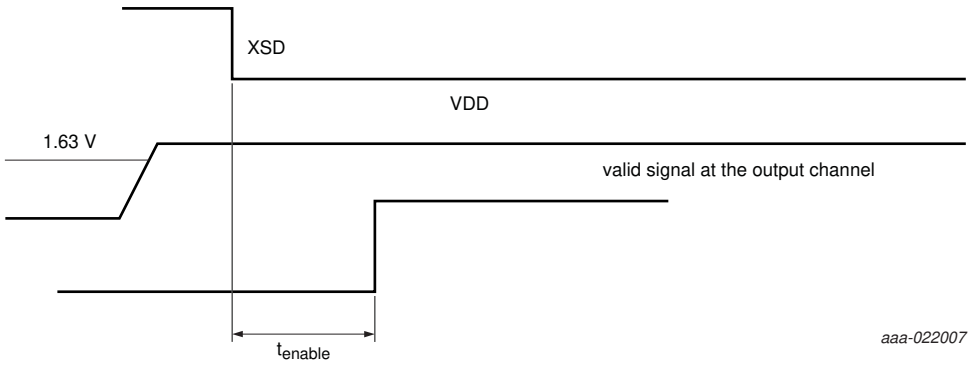
11.1 Device general characteristics

Table 7. General characteristics

Symbol	Parameter	Conditions	Min	Typ[1]	Max	Unit
I_{DD}	supply current	XSD = HIGH (disable)	-	3	10	µA
		XSD = LOW (enable)	-	250	450	µA
$t_{startup}$	start-up time	supply voltage ramping up to valid with XSD = LOW to channel specified operating characteristics	-	-	30	µs
t_{en}	enable time	XSD going LOW to channel specified operating characteristics	-	90	220	µs
t_{rcfg}	reconfiguration time	SEL state changes[2]	-	18	30	ns

[1] Typical values are at VDD = 1.8 V; T_{amb} = 25 °C, and maximum loading

[2] Smooth transition without glitch



Enable time is when valid VDD is available and t = 0 starts when XSD makes transition from HIGH to LOW

Fig 5. Enable time definition

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11.2 Switch channel characteristics

Table 8. Dynamic and static characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
DDIL	differential insertion loss	Channel is off				
		f = 5 GHz	-	–20	-	dB
		f = 100 MHz	-	–40	-	dB
		Channel is on				
		f = 5 GHz	-	–1.4	-	dB
		f = 2.5 GHz	-	–0.9	-	dB
		f = 100 MHz	-	–0.7	-	dB
B_{-3dB}	bandwidth		-	12	-	GHz
DDRL	differential return loss	f = 5 GHz	-	–12	-	dB
		f = 2.5 GHz	-	–16	-	dB
DDNEXT	High-Speed Differential near-end crosstalk	A0 to A1 or B0 to B1 or C0 to C1 ports				
		f = –5 GHz	-	-	–37	dB
DDFEXT	High-Speed far-end crosstalk	A to B or A to C ports (or vice versa)				
		f = –5 GHz	-	-	–20	dB
V_I	input voltage	Switch I/O pins	–0.3	-	2.4	V
V_{IC}	Common-mode input voltage	for all switch ports	0	-	2.0	V
V_{ID_PP}	Differential input voltage		-	1.2	1.6	V
I_{IH}	HIGH-level input leakage current	High–speed switch I/O; A, B and C ports; V_I = 2.0 V	-	-	1.5	µA
I_{IL}	LOW-level input leakage current	V_I = GND	-	-	1.5	µA
V_{IK}	Input negative clamping voltage	Voltage on high-speed channel pins; II = –18 mA	-	-	–1.2	V
t_{PD}	propagation delay	From A port to B or C port or vice versa	-	33	45[1]	ps
t_{sk}	Intra-pair skew	Skew between P and N for all the ports	-	6	-	ps

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Table 8. Dynamic and static characteristics *…continued*

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
R_{onse}	single-end ON-state resistance	Switch ON resistance with source current is 18 mA	-	10	14	Ω
Z_{input}	DC CM input impedance	XSD = High and V_I > 0 V	-	3000[1]	-	KΩ
C_{in}	input capacitance at 2.5 GHz	VDD = 1.8 V; V_I = 1.4 V or floating	-	622[1]	-	fF

[1] Guaranteed by design

11.3 Control signals characteristics

Table 9. SEL input buffer characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{IH}	HIGH-level input voltage		1.4	-	-	V
V_{IL}	LOW-level input voltage		−0.3	-	0.4	V
I_{IH}	HIGH-level input leakage current	Measured with input at V_I = VDD	-	-	1.5	μA
I_{IL}	LOW-level input leakage current	Measured with input at V_I = 0 V	-	-	1.5	μA

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Table 10. XSD input buffer characteristics

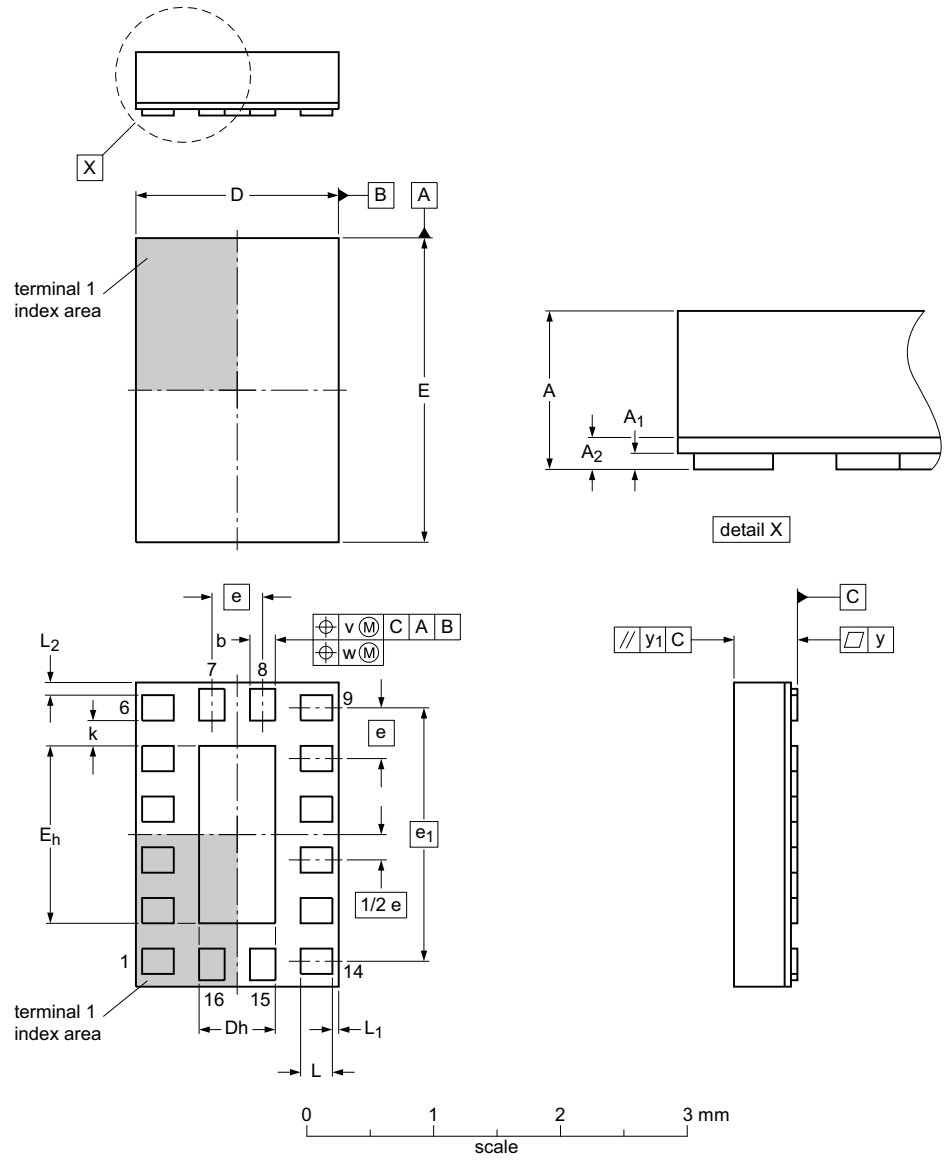
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{IH}	HIGH-level input voltage		0.75 % VDD	-	-	V
V_{IL}	LOW-level input voltage		−0.3	-	0.25 % VDD	V
I_{IH}	HIGH-level input leakage current	Measured with input at V_I = VDD	-	-	1.5	μA
I_{IL}	LOW-level input leakage current	Measured with input at V_I = 0 V	-	-	1.5	μA

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12. Package outline

HUQFN16: plastic thermal enhanced Ultra thin quad flat package; no leads; 16 terminals; body 2.4 x 1.6 x 0.5 mm **SOT1832-1**



Dimensions (mm are the original dimensions)

Unit		A	A_1	A_2	b	D	D_h	E	E_h	e	e_1	k	L	L_1	L_2	v	w	y	y_1
	max	0.55	0.05		0.25	1.65	0.65	2.45	1.45			0.25	0.30	0.10	0.15				
mm	nom	0.50	0.03	0.10	0.20	1.60	0.60	2.40	1.40	0.4	2.0	0.20	0.25	0.05	0.10	0.1	0.05	0.05	0.1
	min	0.45	0.00		0.15	1.55	0.55	2.35	1.35			0.15	0.20	0.01	0.05				

sot1832-1_po

Outline version	References				European projection	Issue date
	IEC	JEDEC	JEITA			
SOT1832-1	- - -	- - -	- - -			~~16-01-21~~ 16-02-15

Fig 6. Package outline SOT1832-1 (HUQFN16)

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13. Packing information

13.1 SOT1832-1 (HUQFN16); Reel pack, SMD, 13" Q1/T1 standard product orientation; Orderable part number ending ,118 or J; Ordering code (12NC) ending 118

13.1.1 Packing method

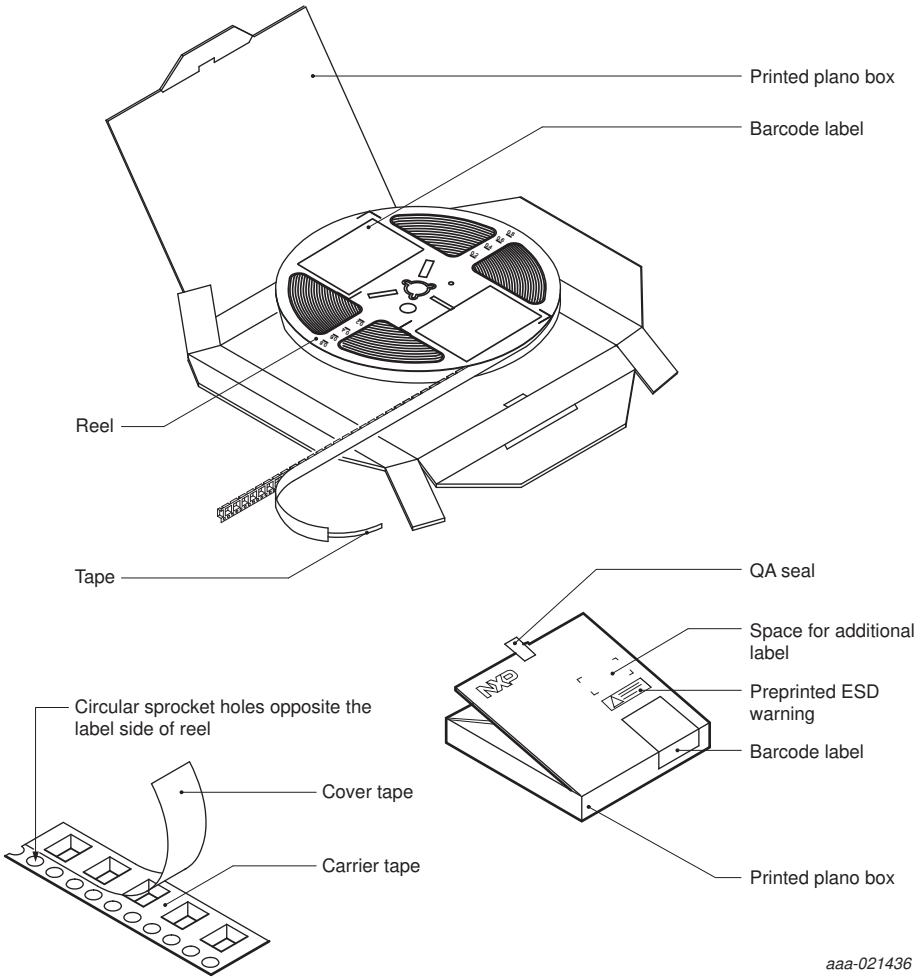


Fig 7. Reel dry pack for SMD: Light weight reel

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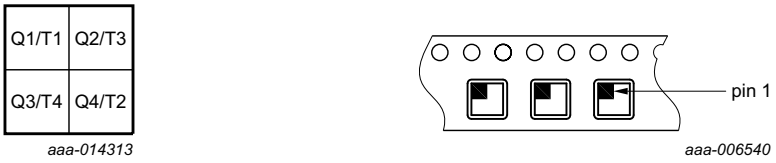
Table 11. Dimensions and quantities

Reel dimensions d × w (mm) [1]	SPQ/PQ (pcs) [2]	Reels per box	Outer box dimensions l × w × h (mm)
330 × 8	10000	1	342 × 338 × 27

[1] d = reel diameter; w = tape width.

[2] Packing quantity dependent on specific product type.
View ordering and availability details at NXP order portal, or contact your local NXP representative.

13.1.2 Product orientation

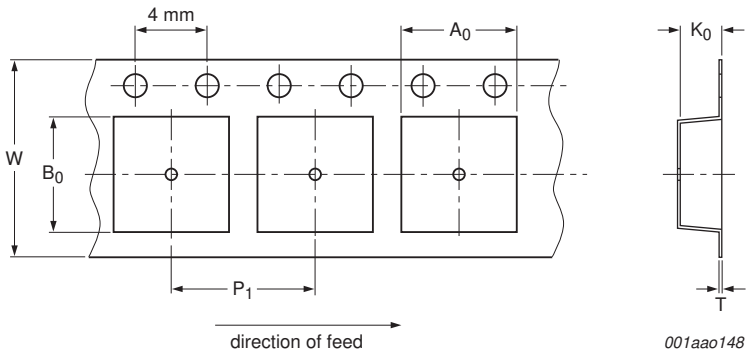


Tape pocket quadrants

Pin 1 is in quadrant Q1/T1

Fig 8. Product orientation in carrier tape

13.1.3 Carrier tape dimensions



Not drawn to scale.

Fig 9. Carrier tape dimensions

Table 12. Carrier tape dimensions
In accordance with IEC 60286-3.

A_0 (mm)	B_0 (mm)	K_0 (mm)	T (mm)	P_1 (mm)	W (mm)
1.79 ± 0.05	2.50 ± 0.05	0.65 ± 0.05	0.23 ± 0.02	4.0 ± 0.5	8.0 ± 0.3/-0.1

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13.1.4 Reel dimensions

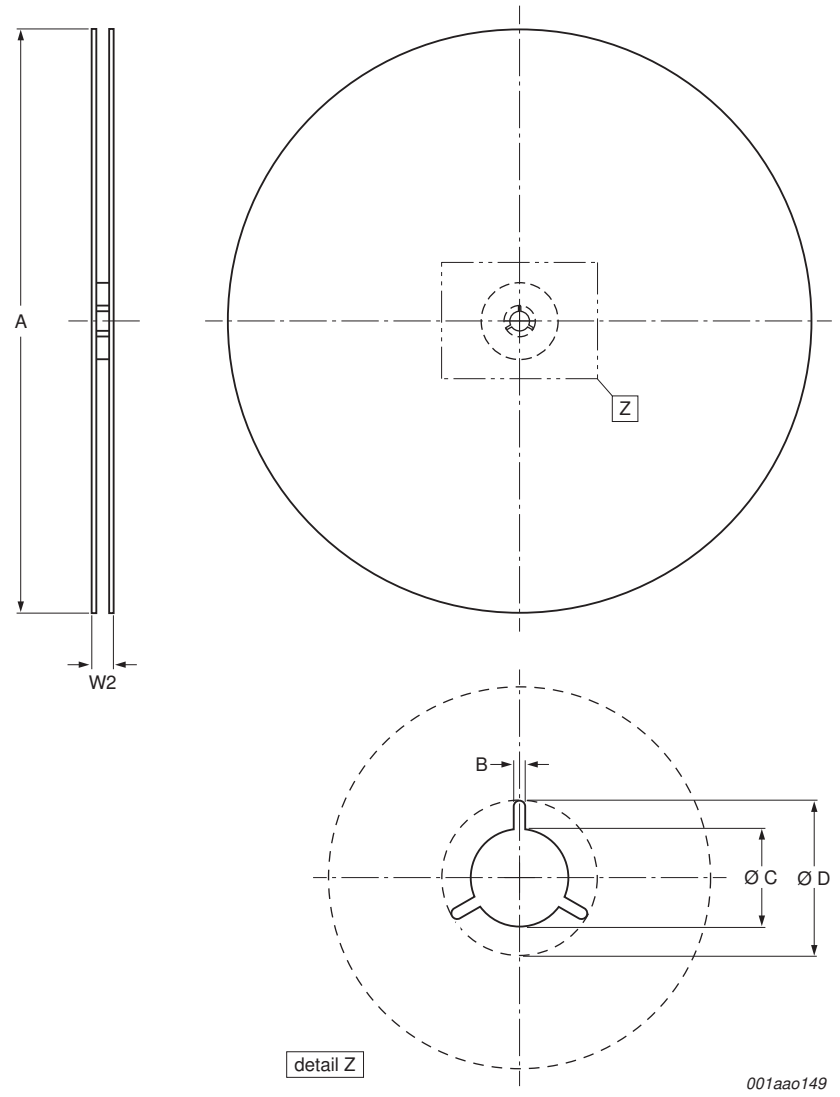


Fig 10. Schematic view of reel

Table 13. Reel dimensions

In accordance with IEC 60286-3.

A [nom] (mm)	W2 [max] (mm)	B [min] (mm)	C [min] (mm)	D [min] (mm)
330	14.4	1.5	12.8	20.2

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13.1.5 Barcode label

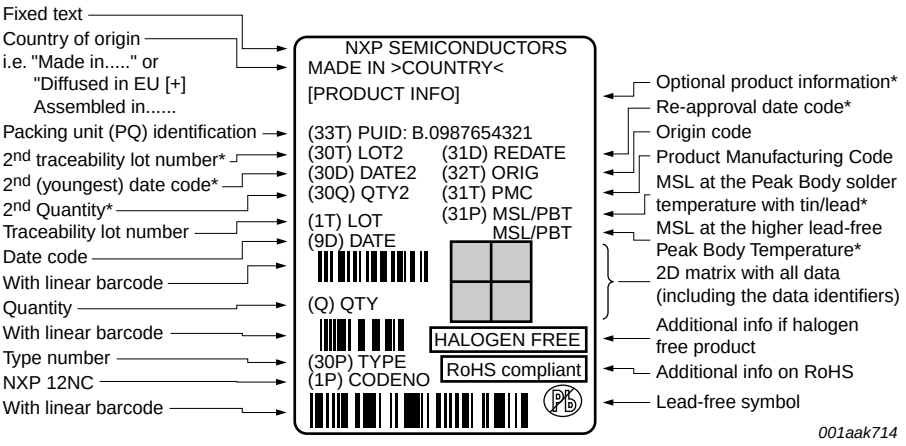


Fig 11. Example of typical box and reel information barcode label

Table 14. Barcode label dimensions

Box barcode label **l × w (mm)**	**Reel barcode label** **l × w (mm)**
100 × 75	36 × 75

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14. Soldering of SMD packages

This text provides a very brief insight into a complex technology. A more in-depth account of soldering ICs can be found in Application Note *AN10365 "Surface mount reflow soldering description"*.

14.1 Introduction to soldering

Soldering is one of the most common methods through which packages are attached to Printed Circuit Boards (PCBs), to form electrical circuits. The soldered joint provides both the mechanical and the electrical connection. There is no single soldering method that is ideal for all IC packages. Wave soldering is often preferred when through-hole and Surface Mount Devices (SMDs) are mixed on one printed wiring board; however, it is not suitable for fine pitch SMDs. Reflow soldering is ideal for the small pitches and high densities that come with increased miniaturization.

14.2 Wave and reflow soldering

Wave soldering is a joining technology in which the joints are made by solder coming from a standing wave of liquid solder. The wave soldering process is suitable for the following:

- Through-hole components
- Leaded or leadless SMDs, which are glued to the surface of the printed circuit board

Not all SMDs can be wave soldered. Packages with solder balls, and some leadless packages which have solder lands underneath the body, cannot be wave soldered. Also, leaded SMDs with leads having a pitch smaller than ~0.6 mm cannot be wave soldered, due to an increased probability of bridging.

The reflow soldering process involves applying solder paste to a board, followed by component placement and exposure to a temperature profile. Leaded packages, packages with solder balls, and leadless packages are all reflow solderable.

Key characteristics in both wave and reflow soldering are:

- Board specifications, including the board finish, solder masks and vias
- Package footprints, including solder thieves and orientation
- The moisture sensitivity level of the packages
- Package placement
- Inspection and repair
- Lead-free soldering versus SnPb soldering

14.3 Wave soldering

Key characteristics in wave soldering are:

- Process issues, such as application of adhesive and flux, clinching of leads, board transport, the solder wave parameters, and the time during which components are exposed to the wave
- Solder bath specifications, including temperature and impurities

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14.4 Reflow soldering

Key characteristics in reflow soldering are:

- Lead-free versus SnPb soldering; note that a lead-free reflow process usually leads to higher minimum peak temperatures (see Figure 12) than a SnPb process, thus reducing the process window
- Solder paste printing issues including smearing, release, and adjusting the process window for a mix of large and small components on one board
- Reflow temperature profile; this profile includes preheat, reflow (in which the board is heated to the peak temperature) and cooling down. It is imperative that the peak temperature is high enough for the solder to make reliable solder joints (a solder paste characteristic). In addition, the peak temperature must be low enough that the packages and/or boards are not damaged. The peak temperature of the package depends on package thickness and volume and is classified in accordance with Table 15 and 16

Table 15. SnPb eutectic process (from J-STD-020D)

Package thickness (mm)	Package reflow temperature (°C)	
	Volume (mm^3)	
	< 350	≥ 350
< 2.5	235	220
≥ 2.5	220	220

Table 16. Lead-free process (from J-STD-020D)

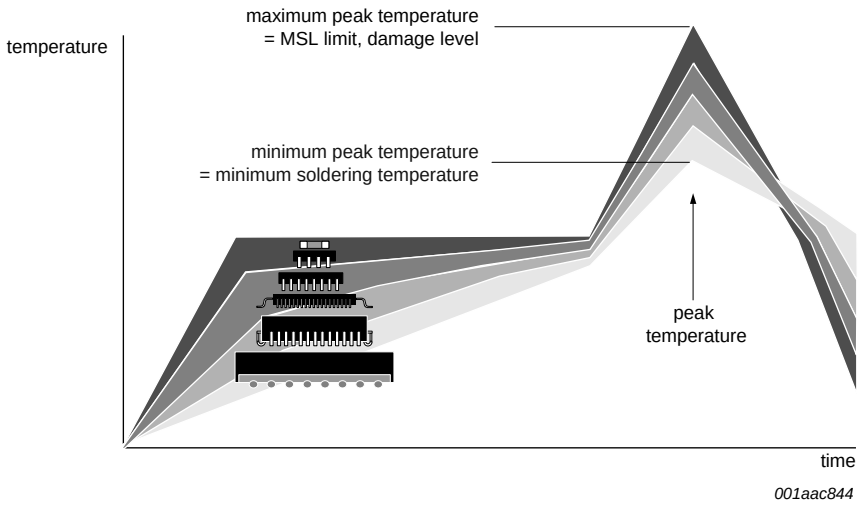
Package thickness (mm)	Package reflow temperature (°C)		
	Volume (mm^3)		
	< 350	350 to 2000	> 2000
< 1.6	260	260	260
1.6 to 2.5	260	250	245
> 2.5	250	245	245

Moisture sensitivity precautions, as indicated on the packing, must be respected at all times.

Studies have shown that small packages reach higher temperatures during reflow soldering, see Figure 12.

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MSL: Moisture Sensitivity Level

Fig 12. Temperature profiles for large and small components

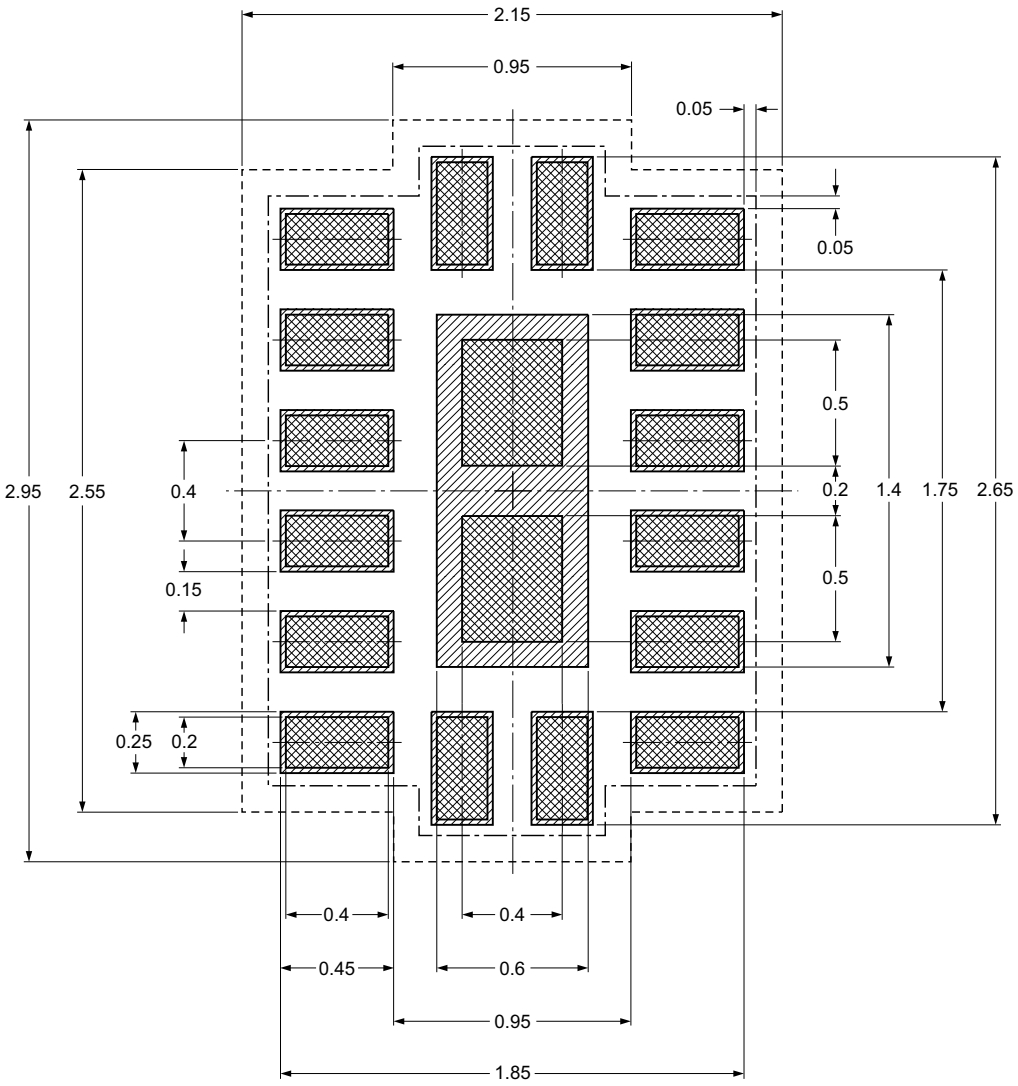
For further information on temperature profiles, refer to Application Note *AN10365 "Surface mount reflow soldering description"*.

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15. Soldering: PCB footprint

Footprint information for reflow soldering of HUQFN16 package **SOT1832-1**



recommended stencil thickness: 0.1 mm

occupied area

solder resist

solder lands

solder paste

Dimensions in mm

Issue date ~~16-03-09~~ 16-03-15

sot1832-1_fr

Fig 13. PCB footprint for SOT1832-1 (HUQFN16); reflow soldering

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16. Abbreviations

Table 17. Abbreviations

Acronym	Description
CDM	Charged Device Model
Gbps	Gigabits per second
HBM	Human Body Model

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17. Revision history

Table 18. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
CBTU02043 v.3	20180719	Product data sheet	-	CBTU02043 v.2
Modifications:	Table 2 “Ordering options”, corrected temperature range from “−40 °C to +85 °C” to “−10 °C to +85 °C”			
CBTU02043 v.2	20180423	Product data sheet	-	CBTU02043 v.1.1
Modifications:	Table 8 “Dynamic and static characteristics”, t_{PD}: Tightened performance spec from 80 ps (typ) to 33ps (typ), 45ps (max)			
CBTU02043 v.1.1	20170531	Product data sheet	-	CBTU02043 v.1
Modifications:	• Removed “Company Confidential” watermark, released to public			
CBTU02043 v.1	20161102	Product data sheet	-	-

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18. Legal information

18.1 Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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